MOSFETs Silicon N-Channel MOS

SSM3K62TU

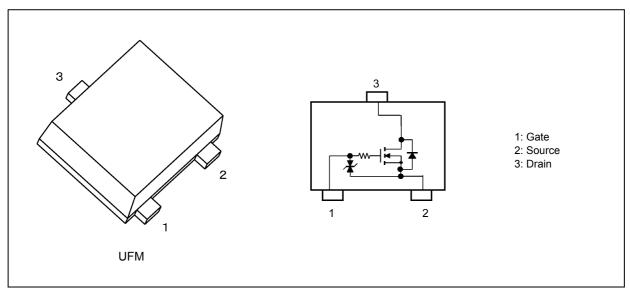
1. Applications

- Power Management Switches
- DC-DC Converters

2. Features

- (1) AEC-Q101 qualified (Please see the orderable part number list)
- (2) 1.2-V drive
- (3) Low drain-source on-resistance
 - : R_{DS(ON)} = 43 mΩ (typ.) (@V_{GS} = 4.5 V)
 - $R_{\rm DS(ON)}$ = 50 m Ω (typ.) (@V_{\rm GS} = 2.5 V)
 - $\mathrm{R}_{\mathrm{DS(ON)}}$ = 60 m Ω (typ.) (@V_{\mathrm{GS}} = 1.8 V)
 - $\mathrm{R}_{\mathrm{DS(ON)}}$ = 70 m Ω (typ.) (@V_{\mathrm{GS}} = 1.5 V)
 - $\mathrm{R}_{\mathrm{DS(ON)}}=98~\mathrm{m}\Omega$ (typ.) (@V_{\mathrm{GS}}=1.2~\mathrm{V})

3. Packaging and Pin Assignment



4. Orderable part number

Orderable part number	AEC-Q101		Note			
SSM3K62TU,LF	—		General Use			
SSM3K62TU,LXGF	M3K62TU,LXGF YES (Note 1)		Unintended Use	(Note 1)		
SSM3K62TU,LXHF	YES		Automotive Use			

Note 1: For more information, please contact our sales or use the inquiry form on our website.

5. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25$ °C)

Characteristics				Rating	Unit
Drain-source voltage			V _{DSS}	20	V
Gate-source voltage			V _{GSS}	±8	
Drain current (DC)		(Note 1)	Ι _D	0.8	A
Drain current (pulsed)		(Note 1), (Note 2)	I _{DP}	1.6	1
Power dissipation		(Note 3)	PD	500	mW
Power dissipation	(t < 1s)	(Note 3)	P _D	1000	mW
Channel temperature			T _{ch}	150	°C
Storage temperature			T _{stg}	-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

- Note 1: Ensure that the channel temperature does not exceed 150°C.
- Note 2: Pulse width (PW) \leq 10 ms, duty \leq 1%
- Note 3: Device mounted on an FR4 board. (FR4, 25.4 mm \times 25.4 mm \times 1.6 mm, Cu pad: 645 mm²)
- Note: The MOSFETs in this device are sensitive to electrostatic discharge. When handling this device, the worktables, operators, soldering irons and other objects should be protected against anti-static discharge.
- Note: The channel-to-ambient thermal resistance, R_{th(ch-a)}, and the drain power dissipation, P_D, vary according to the board material, board area, board thickness and pad area. When using this device, be sure to take heat dissipation fully into account.

6. Electrical Characteristics

6.1. Static Characteristics (Unless otherwise specified, Ta = 25 °C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	V_{DS} = 0 V, V_{GS} = ±8 V			±10	μA
Drain cut-off current		I _{DSS}	V _{DS} = 10 V, V _{GS} = 0 V		_	1	
Drain-source breakdown voltage		V _{(BR)DSS}	I _D = 1 mA, V _{GS} = 0 V	20	_	—	V
Drain-source breakdown voltage	(Note 1)	V _{(BR)DSX}	I _D = 1 mA, V _{GS} = -5 V	15	_	_	
Gate threshold voltage	(Note 2)	V _{th}	V _{DS} = 3 V, I _D = 1 mA	0.4	0.6	1.0	
Drain-source on-resistance	(Note 3)	R _{DS(ON)}	I _D = 100 mA, V _{GS} = 1.2 V	—	98	432	mΩ
			I _D = 200 mA, V _{GS} = 1.5 V		70	139	
			I _D = 600 mA, V _{GS} = 1.8 V		60	89	
			I _D = 800 mA, V _{GS} = 2.5 V		50	68	
			I _D = 800 mA, V _{GS} = 4.5 V		43	57	
Forward transfer admittance	(Note 3)	Y _{fs}	V _{DS} = 3 V, I _D = 200 mA	—	3.0	—	S

Note 1: If a reverse bias is applied between gate and source, this device enters V(BR)DSX mode. Note that the drainsource breakdown voltage is lowered in this mode.

Note 3: Pulse measurement.

6.2. Dynamic Characteristics (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V,	_	177	_	pF
Reverse transfer capacitance	C _{rss}	f = 1 MHz	_	17	_	
Output capacitance	C _{oss}		_	52	_	
Switching time (turn-on time)	t _{on}	V _{DD} = 10 V, I _D = 800 mA,	_	332	—	ns
Switching time (turn-off time)	t _{off}	V_{GS} = 0 to 4.5 V, R_{G} = 50 Ω		2653	_	

6.3. Switching Time Test Circuit

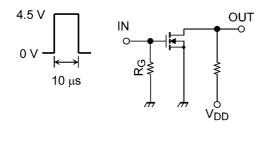


Fig. 6.3.1 Switching Time Test Circuit

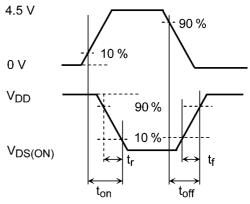


Fig. 6.3.2 Input Waveform/Output Waveform

6.4. Gate Charge Characteristics (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	V _{DD} = 10 V, I _D = 800 mA,	_	2.0	—	nC
Gate-source charge 1	Q _{gs1}	V _{GS} = 4.5 V	_	1.3	_	
Gate-drain charge	Q _{gd}		_	0.6		
2016-2021		3			2021-	05-28

Note 2: Let V_{th} be the voltage applied between gate and source that causes the drain current (I_D) to below (1 mA for this device). Then, for normal switching operation, V_{GS(ON)} must be higher than V_{th}, and V_{GS(OFF)} must be lower than V_{th} . This relationship can be expressed as: $V_{GS(OFF)} < V_{th} < V_{GS(ON)}$. Take this into consideration when using the device.

6.5. Source-Drain Characteristics (Unless otherwise specified, $T_a = 25$ °C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Diode forward voltage	(Note 1)	V_{DSF}	$I_{\rm D}$ = -800 mA, $V_{\rm GS}$ = 0 V	_	-0.6	-1.2	V

Note 1: Pulse measurement.

7. Marking

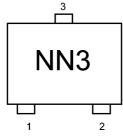
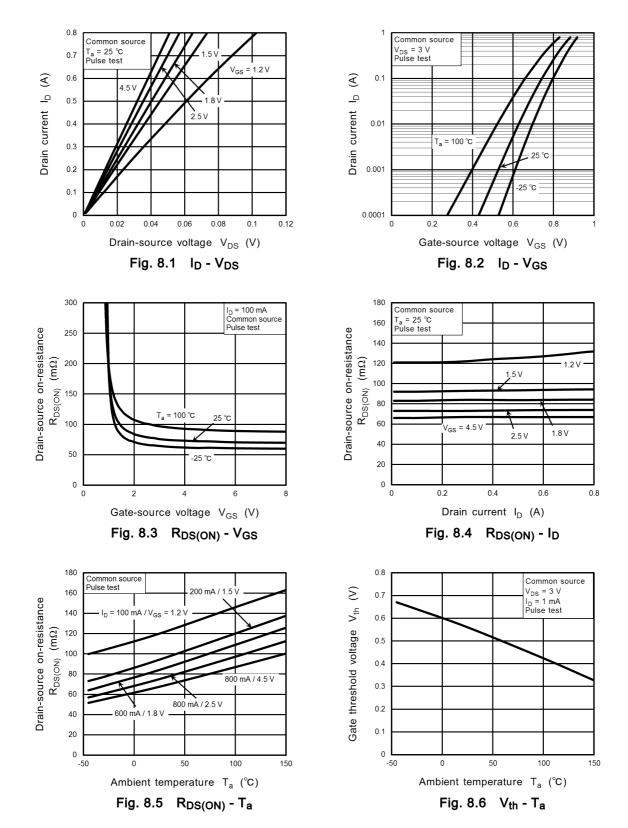
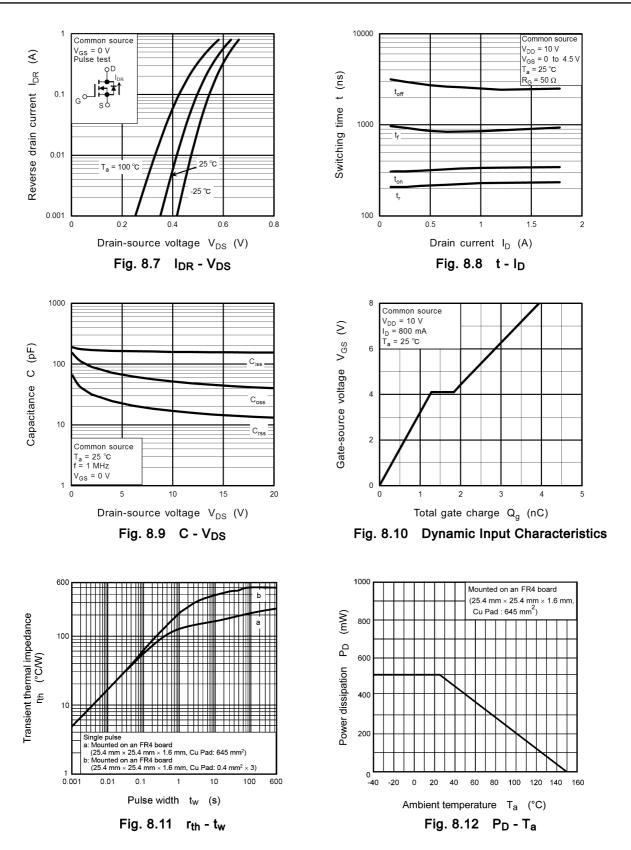


Fig. 7.1 Marking

8. Characteristics Curves (Note)





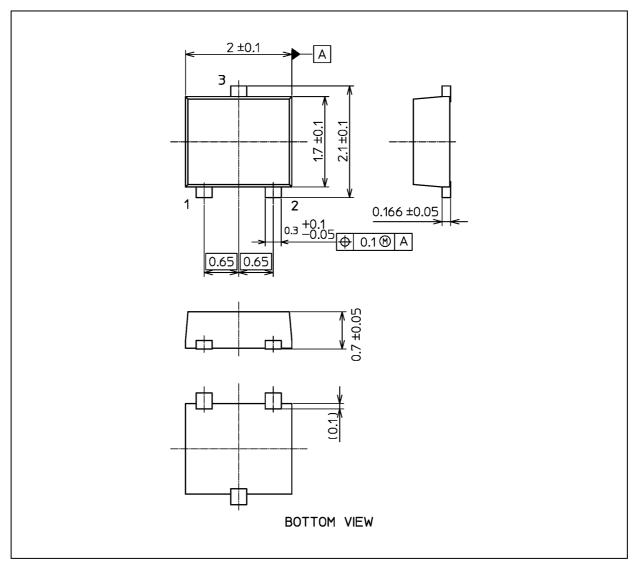
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



SSM3K62TU

Package Dimensions

Unit: mm



Weight: 6.6 mg (typ.)

Package Name(s)

Nickname: UFM

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